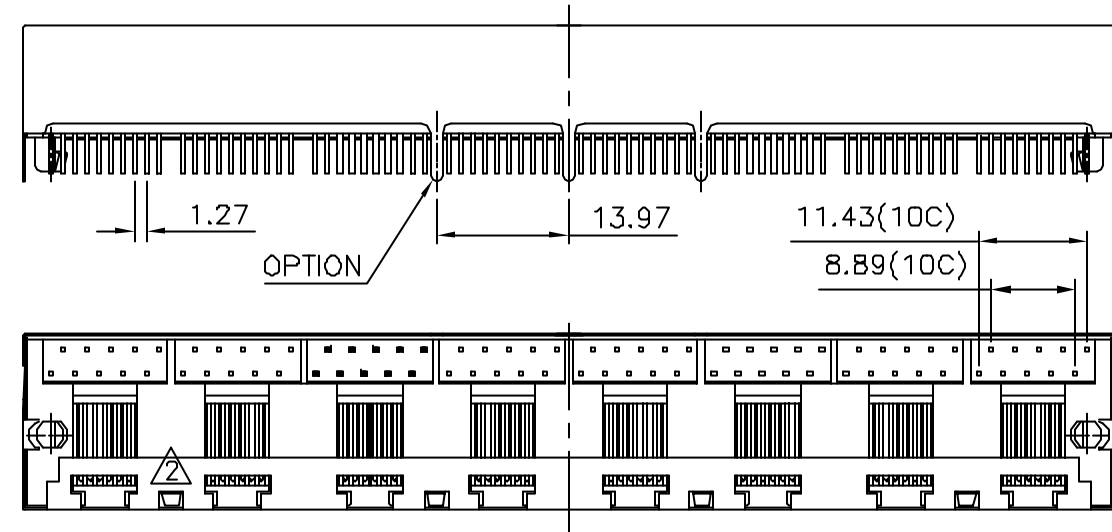
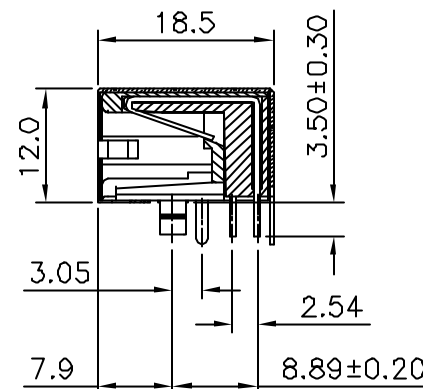
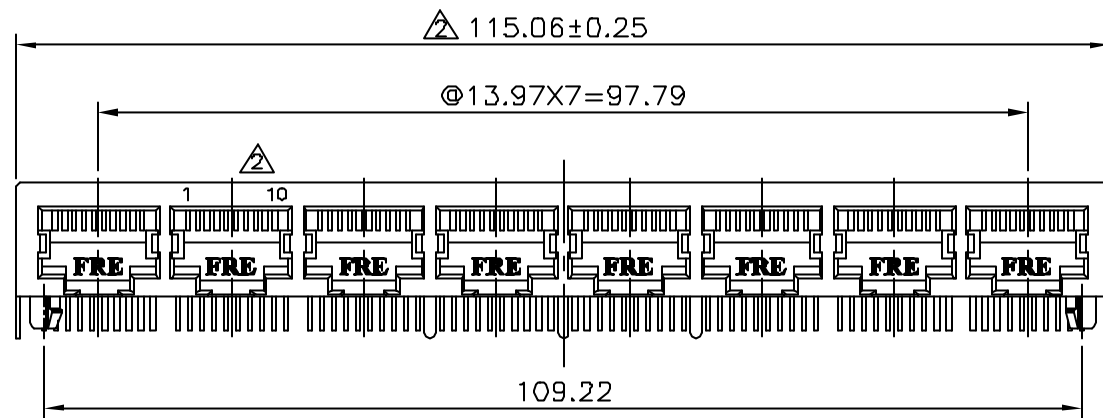


| REVISION RECORD | | | | |
|-----------------|-----|---------------------------------------|-------------------|------|
| REV | ECO | DESCRIPTION | DRFT | CHKD |
| △ | | MODIFY PART NO. | 1/9/02' CHI | |
| △ | | Add Pin No. & Modify View & Dimension | YUAN 01/14/04' | |



NOTES:

ELECTRICAL:

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 35 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

- HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

- STORAGE : -40°C TO +85°C.
- OPERATION: -40°C TO +85°C.

MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68, SUBPART F.

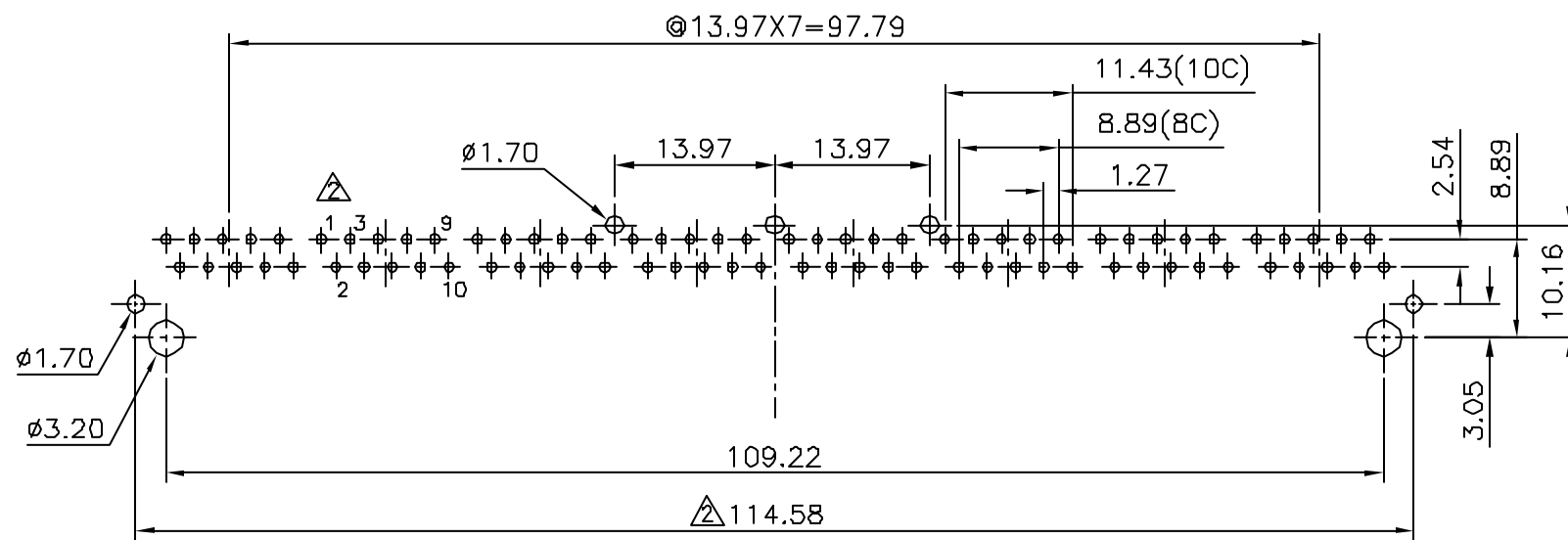
CUL&UL FILE NO. E163191

PART NUMBER: E560X-XXG08X

- 8- 8 CONTACTS
- 1-10 CONTACTS
- 1- 3u"
- 2- 6u"
- 3-15u"
- 4-30u"
- 5-50u"
- 6-Pd 20u"

- 0- TIN
- 4- NICKEL

- 2- BEHIND PEG 3.05
- H- BEHIND PEG 3.05, W/ 3 GROUNDING TABS
- J- BEHIND PEG 3.05, W/ 5 GROUNDING TABS



PC Board Layout t=1.60mm
Component Side Shown

| | | | | | | | |
|----------------|----------------------------|------------------|----------------------|-------------------------------|--------------|--|--|
| DETACHED LISTS | MM (INCH) | DFTO CHI | DATE 12/04/00' | FULL RISE ELECTRONIC CO., LTD | | | |
| | TOLERANCES EXCEPT AS NOTED | CHKD RIK | DATE 01/14/04' | | | TITLE RJ45 SIDE ENTRY PCB GAND JACK | |
| | MATERIAL : | MFO LMJ | DATE 01/14/04' | | | | |
| | ANGLES ± 0.5 | APPVLYUAN | DATE 01/14/04' | | | | |
| MM | ± | QT'Y : | DRAWING NO. GE563A47 | | SIZE | REV | |
| .0 ±0.2 | ± | FINISH : | /PART NO. SEE NOTE | | A3 | 2 | |
| .00 ±0.15 | ± | SCALE : 1.25 : 1 | DO NOT SCALE DRAWING | | SHEET 1 OF 1 | | |
| .000 ±0.075 | ± | | | | | | |